# H7 L C &\$% @GE & 5V CMOS DIL14 TCXO

### **Features and Benefits**

High frequency stability(up to ±0.5 ppm over -40°C to +85°C) Low power consumption (up to 15 mA) DIL14 package design 5V CMOS output

### **Typical Applications**

Microwave Communication Mobile Devices

### **Description**

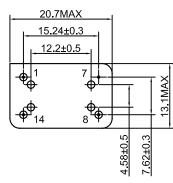
TCXO2013LSQ2 offers high frequency stability and low power consumption in DIL14 package with wide range of stability vs. operating temperature options to suit the different applications needs.

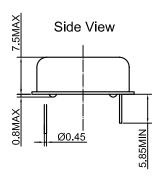
# **Mechanical Drawing & Pin Connections**

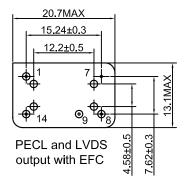
**Drawing No:** 

MD1400\*\*-(

#### **Bottom View**







#### Pin Connections: (Without EFC)

PIN#	Symbol	CONNECTION			
1	N.C or Comp OUT	No Connection or Complementary RF Output (PECL and LVDS)			
7	GND Ground				
8	RF OUT	RF Output			
9	Pin Not Present				
14	Vs	Supply Voltage			

#### Pin Connections: (With EFC)

PIN#	Symbol	CONNECTION
1	Vc	Control Voltage(EFC)
7	GND	Ground
8	RF OUT	RF Output
9	Comp OUT	Complementary RF Output (PECL and LVDS)
14	Vs	Supply Voltage

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Unit in mm 1mm = 0.0394 inches



# Dynamic Engineers Inc.

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# **Specifications**

Oscillator	Sym	Condition	Value			Unit	Note
Specification	Sylli	Condition	Min.	Тур.	Max.	Ullit	Note
Frequency Range			1		200	MHz	
Output Waveform				HCMOS			
Output Load				15		pF	
Amplitude			According t	o relevant L	ogic Standard		
Power Supply							
Supply Voltage	Vs		4.75	5.00	5.25	V	
Current Consumption (Note 2)				15 ~ 50		mA	
Frequency Adjustment Range							
Mechanical (internal trimmer)			±3			ppm	Ordering Option = blank
Electronic Frequency Control (EFC)			±5			ppm	Ordering Option = "V"
EFC Voltage	V <sub>C</sub>		0.5	2.5	4.5	V	
EFC Slope	$\Delta f / \Delta V_C$			Positive			
EFC Input Impedance			100			kΩ	
Frequency Stability							
Vs Operating Temperature			±0.5		±5.0	ppm	Refer to ordering options
Vs Supply Voltage changes	Vs	±5%		±0.1	±0.3	ppm	
Vs Load changes		±10%			±0.2	ppm	
Long Term Aging Per Year		@ +40°C			±1.0	ppm	
<b>Environmental Conditions</b>							
Operating Temperature Range			-40		+85	°C	Refer to ordering options
Storage Temperature Range			-55		+105	°C	
Enclosure (see drawing) L x W x H		max	2	0.7 x 13.1 x	7.5	mm	IEC 60679-3 CO 02
Weight					5	g	

#### Notes:

- 1. Terminology and test conditions are according to IEC60679-1 and MIL-PRF-55310, unless otherwise stated
- 2. Depending on frequency and supply voltage
- 3. Reduced package height H = 5.1 mm max. available on request
- 4. All combinations of options might not be available. Please consult DEI for details

# **Absolute Maximum Ratings**

Parameter	Sym	Min	Max.	Unit	Condition
Supply Voltage	$V_S$	-0.5	V <sub>s</sub> +10%	V	V <sub>s</sub> to GND
Control Voltage	V <sub>C</sub>	-0.5	6	V	V <sub>C</sub> to GND

# **Handling and Testing**

Parameter	Procedure	Condition	
Electrostatic Discharge (ESD)			
THD devices	IEC60749-26	HBM	2000V
SMD devices	IEC60749-27 MM		200V
Washable	Yes		
RoHS Compliant	Yes	•	



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# **Ordering Options**

Frequency Stability			erature wer)	Temperature (Upper)		
Code	Stability [ppm]	Code	T (°C)	Code	T (°C)	
1	±0.5	1	0	1	+50	
2	±1.0	2	-10	2	+60	
3	±1.5	3	-20	3	+70	
4	±2.0	4	-30	4	+75	
5	±2.5	5	-40	5	+80	
6	±3.0			6	+85	
7	±3.5					
8	±5.0					

# **Ordering Codes**

Model	EFC	Frequency in MHz (up to 4 digits)	Frequency Stability	Minimum Operating Temperature	Maximum Operating Temperature
TCXO2013LSQ2	_ or "V"	xxx.yyyy	t	w	Z

Example: TCXO2013LSQ2-20.0000-5-5-6 has the following specifications

 $\begin{array}{ll} {\sf EFC} & = {\sf no \ EFC \ control} \\ {\sf Frequency} & = 20.0000 \ {\sf MHz} \\ {\sf Stability} & = \pm 2.5 \ {\sf ppm} \\ {\sf Operating \ Temperature} & = -40^{\circ}{\sf C \ to } +85^{\circ}{\sf C} \\ \end{array}$ 

### **Environmental Conditions**

Test	IEC 60068 Part	IEC 60679-1 Clause	MIL-STD- 202G Method	MIL-STD- 810F Method	MIL-PRF- 55310D Clause	Test Conditions (IEC)
Sealing tests (if applicable)	2-17	5.6.2	112E		3.6.1.2	Gross leak: Test Qc, Fine leak: Test Qk
Solderability Resistance to soldering heat	2-20 2-58	5.6.3	208H 210F		3.6.52 3.6.48	Test Ta Method 1 Test Td <sub>1</sub> Method 2 Test Td <sub>2</sub> Method 2
Shock	2-27	5.6.8	213B	516.4	3.6.40	Test Ea, 3 x per axes 100g, 6 ms half-sine pulse
Vibration sinusoidal	2-6	5.6.7.1	201A 204D	516.4-4	3.6.38.1 3.6.38.2	Test Fc, 30 min per axes, 10 Hz – 55 Hz 0,75mm; 55 Hz – 2 kHz, 10g
Vibration, random	2-64	5.6.7.3	214A	514.5	3.6.38.3 3.6.38.4	Test Fdb
Endurance tests - aging - extended aging		5.7.1 5.7.2	108A		4.8.35	30 days @+85°C 1000h, 2000h, 8000h @ +85°C